DN A01198 US

DN A01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re application of

Carlos Alfonso Cruz, et al.

Application No.: 10/082,274 **Confirmation No.:** 3671

Filed: February 25, 2002

For: NON-GELLING HIGH MOLECULAR

WEIGHT POLYMER COMPOSITIONS AND THERMOPLASTIC BLENDS

THEREOF

Group No. : 1711

Examiner: Olga Asinovsky

Notice of Allowance:

Mailed: April 14, 2004

Issue Fee Due: July 14, 2004

Mail Stop **ISSUE FEE**Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. § 1.312

X

Sir:

A Notice of Allowance was mailed for the above-identified patent application on April 14, 2004 and set a due date of July 14, 2004 for payment of the issue fee. The issue has not yet been paid. In the foregoing circumstances, Applicants wish to amend the present application as follows.

AMENDMENTS TO THE TITLE begin on page 2 of this paper.

REMARKS begin on page 3 of this paper.



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Atty Docket No.: A01198

MMB/yv

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Group Art Unit: 1711

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MAIL STOP: ISSUE FEE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

CERTIFICATE OF MAILING

Sir:

I hereby certify that the following correspondence is being deposited with the U.S. Postal Service as first-class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated next to my signature below:

Amendment After Allowance Remarks Return Receipt Postcard

Data 04/19/2004

Motte Vylianese_ Signature DN A01198 US PATENT

AMENDMENTS TO THE TITLE

Please replace the tile currently on record for the present application with the following re-written title:

NON-GELLING HIGH MOLECULAR WEIGHT POLYMER COMPOSITIONS AND THERMOPLASTIC BLENDS THEREOF

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